Special Issue

Laser Material Processing and Thermal Joining Process

Message from the Guest Editor

This special issue addresses original scientific articles and detailed reviews related to important and novel developments in the field of laser material processing and thermal joining processes.Both fields are of great importance, and innovative approaches in process design and systems engineering are increasing the range of applications for cutting-edge industries, for example in electromobility and other branches. This special issue focusses specifically on contributions dealing with novelties in process design, material science and systems engineering and their interaction in the context of laser material processing and thermal joining processes

Guest Editor

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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